

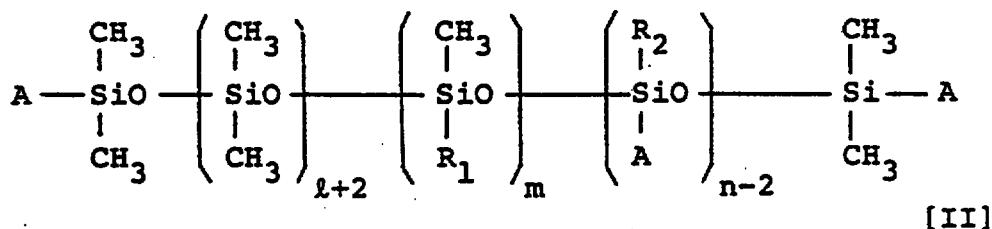
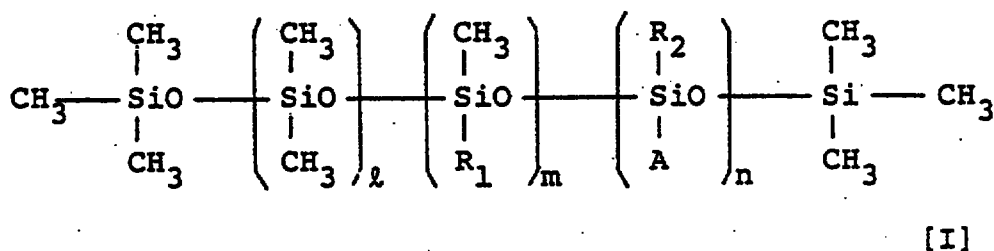
ABSTRACT

EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR SEALING

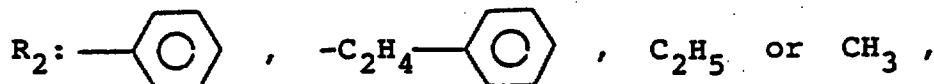
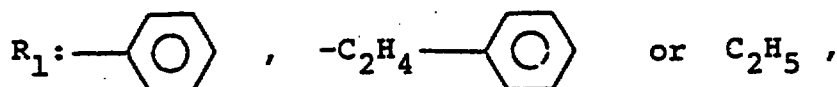
An epoxy resin composition for semiconductor sealing, comprising as essential components:

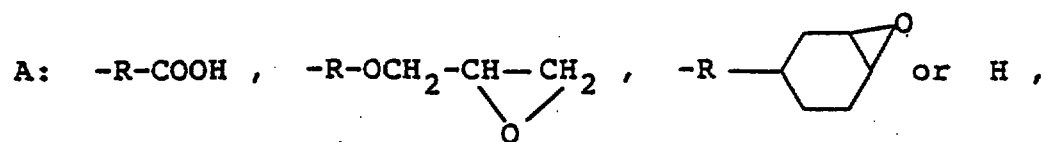
(A) an epoxy resin,

(B) a phenolic resin curing agent comprising 30-100% by weight, based on the total amount of the phenolic resin curing agent, of a silicone-modified phenolic resin curing agent obtained by reacting a phenolic resin with at least one of silicone compounds represented by the following formulas [I] and [II]



wherein





R: a lower alkylene group,

$$10 \leq N = l + m + n + 2 \leq 200 ,$$

$$0 \leq m/N \leq 0.1 , \text{ and } 5 \leq N/n \leq 50 ,$$

(C) an inorganic filler, and

(D) a curing accelerator.